



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STA8089GATR	A0EG*V839BDX	A	ZY1A	2016-06-27
Amount	UoM	Unit type	ST ECOPACK Grade	
135.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x1.0	56	flat	
Comment	Package: VFQFPN 7X7X1.0 56L PITCH 0.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A0EG*V839BDX						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	5.291	mg	supplier	die	Silicon (Si)	7440-21-3		4.436	mg	838405	32859	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.030	mg	5670	222	
				supplier	metallization	Copper (Cu)	7440-50-8		0.179	mg	33831	1326	
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.456	mg	86184	3378	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1512	59	
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	189	7	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	189	7	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	7749	304	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.139	mg	26271	1030	
				Leadframe	Copper & its alloys	77.227	mg	supplier	alloy	Copper (Cu)	7440-50-8		73.720
supplier	alloy	Iron (Fe)	7439-89-6						1.777	mg	23010	13163	
supplier	alloy	Zinc (Zn)	7440-66-6						0.091	mg	1178	674	
supplier	alloy	Phosphorus (P)	12185-10-3						0.022	mg	285	163	
supplier	metallization	Silver(Ag)	7440-22-4						1.617	mg	20938	11978	
Die attach	Other organic materials	1.273	mg	supplier	glue	Epoxy Resin	9003-36-5		0.204	mg	160251	1511	
				supplier	glue	Silver(Ag)	7440-22-4		1.069	mg	839749	7919	
Bonding wires	Precious metals	0.136	mg	supplier	wire	Gold (Au)	7440-57-5		0.135	mg	992647	1000	
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	7353	7	
Encapsulation	Other organic materials	50.635	mg	supplier	mold compound	Epoxy Resin	25068-38-6		6.329	mg	124993	46881	
				supplier	mold compound	Silica fused (SiO2)	60676-86-0		44.052	mg	869991	326311	
				supplier	mold compound	Carbon Black	1333-86-4		0.254	mg	5016	1881	
Finishing	Solder	0.438	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.438	mg	1000000	3244	